Call for Paper

The 15th Electronic Circuits World Convention (ECWC15) is the most notable international PCB symposium held every three years in different cities around the world. In the last 40 years, members of the World Electronics Circuit Council (WECC) have taken turns to host this conference.

HKPCA is honored to host ECWC15 in 2020. The conference is scheduled to begin in Hong Kong on 30 November 2020 and conclude at the International Electronics Circuit Exhibition (Shenzhen) in South China on 2 December 2020. The ECWC teams hope to provide a valuable platform to encourage learnings amongst peers and provide the latest on global PCB demand, PCB manufacturing processes as well as technologies to enable them to better cope with the changing market dynamics for trends such as 5G, autonomous driving, smart world and much more. It also aims to promote the domestic PCB industry and economic activities in every country and every region.

We welcome local and international papers and invite you to participate in this international event that occurs only every 3 years...network and share experiences with peers in the PCB and electronics manufacturing industry. For the submission of an abstract for ECWC15, please use our submission form as the attached.

Paper Scope

**Technology**
- T1 Design and Development Tools
- T2 Materials, Components and Traceability
- T3 Manufacturing
  - T3.1 Equipment
  - T3.2 Technology
  - T3.3 Process Development
  - T3.4 Automation
- T4 Quality, Test and Life Cycle Management
- T5 PCB Processes
  - T5.1 Chemical Technology
  - T5.2 Mechanical Technology
  - T5.3 Optical Technology
- T6 Surface Mounting, Assembly and Interconnection

**Management**
- M1 Global Market Trends and Outlook
- M2 Supply Chain Management
- M3 Environment, Health and Safety
- M4 Business Models and Strategy
- M5 Certification and Qualifications
- M6 Total Cost of Ownership and Overall Equipment Efficiency (OEE)
- M7 Industry 4.0/Smart manufacturing
- M8 Traceability/Blockchain
T7 Packaging Technology
   T7.1 System in Package
   T7.2 Wafer-Level Packaging
   T7.3 Panel-Level Packaging

T8 Energy Harvesting/Green Energy

T9 Application Specific Areas
   T9.1 Automotive Electronics and Electromobility
   T9.2 Industrial and Power Electronics
   T9.3 Aerospace and Defence
   T9.4 Medical Electronics
   T9.5 Consumer Electronics

T10. Advanced and Emerging Technologies

T11. 5G Requirements on PCBs

T12. Smart Living Applications

T13. E-Textiles/Smart Textiles

T14. Printed Electronics/Printed Hybrid

Submission Requirements
There are two opportunities for presenting your expertise:

✧ **Oral presentation**
   These will be held within conference sessions addressing key elements of the same topic. Each presentation should last 20 minutes. An extra 5 minutes will be permitted for discussions and questions from the audience.

✧ **Poster presentation**
   Authors will have the chance to present their posters during a special poster session.

Abstract Submission
The synopsis/abstract should be submitted to ecwc15@hkPCA.org as pdf-file and should comprise 2–3 pages.

Selection Process
All submitted abstracts will be presented to the committee for selection. The acceptance of your abstract depends on the following criteria: the content, the preparation, the substance and the relevance of the conference themes. Punctuality and completeness are also criteria. The committee reserves the right to allocate abstracts to a different topic when suitable.

Best Paper Award
The ECWC15 Program Committee will nominate the best abstracts out of all submissions. After the submission of the final papers the winners of the Best Paper Awards will be determined. The awards ceremony will take place on 2 December 2020.

**Submission Deadline:** 31 January, 2020

Hong Kong Printed Circuit Association (HKPCA)
Event Information

Date / Place

- 30 November to 1 December 2020:
  Hong Kong Science Park, Shatin
- 2 December, 2020:
  Shenzhen Convention & Exhibition Center, China
- 2-4 December, 2020: in conjunction with “International Electronics Circuit Exhibition (Shenzhen)”

Organizer

Hong Kong Printed Circuit Association (HKPCA)

Co-Organizer

WECC members:

- CPCA
- EIPC
- ELCINA
- IPC
- IPCA
- KPCA
- JPCA
- THPCA
- TPCA

Implementation Organization

Hong Kong Productivity Council

Funded by

ITC, GSP from Hong Kong SAR

Enquiry

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Hong Kong Productivity Council (HKPC)

Implementation Organization

香港生產力促進局

執行單位

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Ms. Samantha Chan
# Paper Submission Application Form

(Please send this filled form to ecwc15@hk pca.org)

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## Author (Speaker) Information

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<thead>
<tr>
<th>Title</th>
<th>□ Mr. □ Ms. □ Dr. □ Prof.</th>
<th>Nationality</th>
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## Paper Information

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<th>□ Poster □ Oral</th>
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<td>Additional Author(s)</td>
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<td>Abstract (Within 100-300 words)</td>
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